

# 20-3063 POTTING COMPOUND

#### **DESCRIPTION:**

20-3063 is an electronic grade potting and encapsulating compound. This epoxy system is designed for applications requiring an easy and affordable potting process. 20-3063 has an easy to use one to one mix ratio by weight or volume. The resin is pigmented black and the catalyst white for a visual indication that the products have been properly mixed together.

For less filler settling and a slightly higher viscosity use Catalyst 20-3063C HV.

### **FEATURES:**

- Low Viscosity
- Low Cost
- Easy Non-Critical 1:1 Mix Ratio
- Room Temperature Cure
- Electrically Insulating
- Color change for mixing accuracy

#### **TYPICAL SPECIFICATIONS:**

|                                      | 20-3063R Epoxy<br>20-3063C Curing Agent | 20-3063R Epoxy<br>20-3063C HV Curing Agent |
|--------------------------------------|---|--|
| Mix Ratio, By Volume or Weight Color | 1:1                                     | 1:1  |
| Resin                                | Black                                   | Black                                      |
| Catalyst                             | White                                   | White                                      |
| Viscosity, 25°C, cps                 |   |  |
| Resin                                | 5,500                                   | 5,500                                      |
| Catalyst                             | 10,000                                  | 52,000                                     |
| Mixed Viscosity, 25 °C, cps          | 6,700                                   | 10,000                                     |
| Specific Gravity, 25°C, cps          |   |  |
| Resin                                | 1.54                                    | 1.54                                       |
| Catalyst                             | 1.53                                    | 1.53                                       |
| Pot Life, 100 Gram Mass, 25℃         | 45 Minutes                              | 45 Minutes                                 |
| Hardness, Shore D                    | 75 - 80                                 | 75 - 80                                    |
| Temperature Range of Use, ℃          | -40 to 130                              | -40 to 130                                 |
| Dielectric Strength, Volts/mil       | 450                                     | 450  |
| Dielectric Constant, 1mHz            | 4.4                                     | 4.4  |



## **INSTRUCTIONS FOR USE:**

Some settling of fillers is common during transportation and storage. Remix individual components before using.

By weight or volume mix equal parts 20-3063 Resin and Catalyst. Mix thoroughly being careful not to introduce excessive air into the mixture.

Pour and allow material to cure according to one of the following schedules:

24 hours at 25 ℃/77 ℉ 1 hour at 65 ℃/150 ℉ 15 minutes at 100 ℃/212 ℉

#### **IMPORTANT:**

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01/13